

BB02-YN :- 1.0mm (0.039") SMD PIN HEADER, SINGLE ROW, R/A - 02 TO 35 CONTACTS

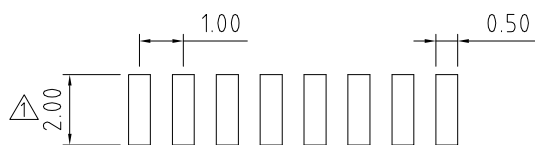
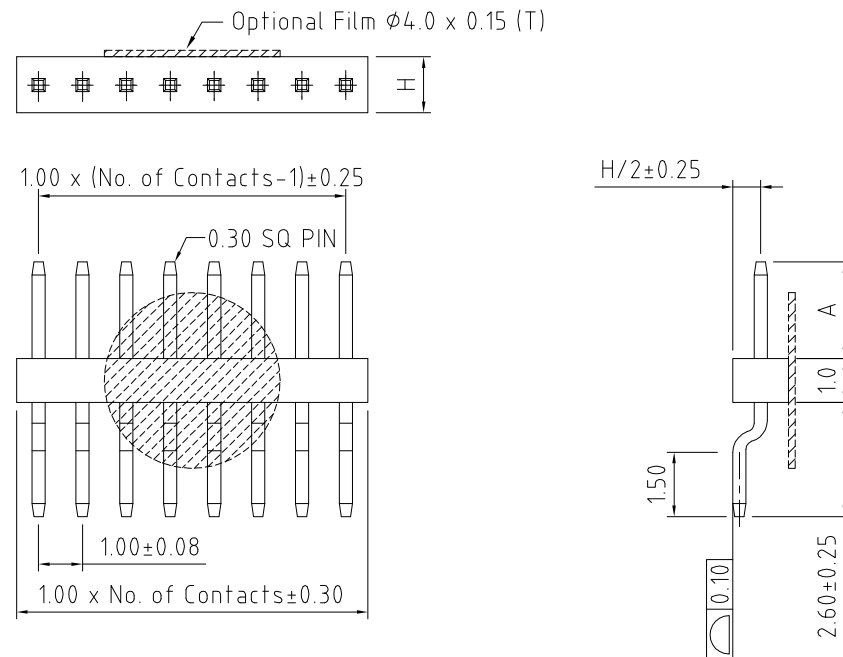
SPECIFICATIONS :

CURRENT RATING	1 AMP
INSULATOR RESISTANCE	1000 MEGOHMS MIN.
CONTACTS RESISTANCE	20 m OHMS MAX.
DIELECTRIC WITHSTANDING	AC 300V
OPERATING TEMPERATURE	-40°C TO +105°C
CONTACT MATERIAL	PHOSPHOR BRONZE
INSULATOR MATERIAL	THERMOPLASTIC, UL 94V-0 STANDARD: LCP+30%G/F OR EQUIVALENT
PLATING	GOLD, TIN, OR SELECTIVE OVER 30-50U" NICKEL
SOLDERABILITY	IR REFLOW: 280°C FOR 10 SEC MANUAL SOLDER: 380°C FOR 3-5 SEC

NOTES:

1. PACKAGING FOR 02 TO 04 CONTACTS IS BOX.

MATES WITH :- BB02-WD
BB02-WE
BB02-WF



RECOMMENDED PC BOARD SMD LAYOUT
(TOLERANCE: ±0.05)

HOW TO ORDER

B B 0 2	-	Y N X X 1	-	X X X	-	X X 0 0 0 0	
NO. OF CONTACTS: 02 TO 35		CONTACT PLATING OPTIONS: K = GOLD FLASH (STANDARD) T = BRIGHT TIN M = MATT TIN		HEIGHT H OPTIONS: A = 1.27MM B = 1.50MM		PACKAGING OPTIONS: 3 = TUBE (SEE NOTE.1) 6 = TAPE & REEL 7 = TAPE & REEL + FILM	PIN LENGTH 'A' (1/10mm) PLEASE SPECIFY PIN LENGTH REQUIRED IN mm I.E. 2.5mm = 25 STANDARD = 15 MINIMUM = 15 MAXIMUM = 6.0 TOL. ±0.25mm

REV. DATE & DRN	10 03/07/09 - CHC RELEASE
11 16/10/09 - NYW	ADD REEL LAYOUT
12 07/10/09 - NYW	REMOVE OPTION 2 & 3 FROM HEIGHT C.
13 30/03/10 - NYW	ADD B HEIGHT OPTION.
14 17/12/10 - NYW	REMOVE HEIGHT C OPTION.
15 25/10/11 - NYW	ADD MIN. & MAX. PIN LENGTH.
16 07/03/12 - NYW	REMOVE PLATING OPTIONS AND C.
17 01/03/13 - NYW	ADD FILM DRAWING.
18 07/03/13 - NYW	CHANGE MAX. PIN# TO 35.

Scale:	8:1
Drawn:	CHC
App'd:	XXX
Date:	7 MAR '13

THIRD ANGLE	Unstated Tolerances: X ± 0.30 X ± 0.25 XX ± 0.15 XXX ± 0.10
Title	PIN HEADER
Revision:	18
Material	SEE NOTE
UNIT:	mm
	NOT TO SCALE

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Type:	BB02-YN
Drawing Number:	BB02-YN
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Drawing	© E and O E